



Nonthermal and Advanced Food Processing Technologies: Industry 4.0 and Sustainability Volume II

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Deadline for manuscript
submissions:
closed (25 March 2022)

Message from the Guest Editors

Dear Colleagues,

The aim of this special issue is to invite groundbreaking research idea focused on application of nonthermal and advanced thermal food processing techniques in research and industry. Review papers on the state of the art of the tools of industry 4.0 and digitalization, including smart manufacturing, simulations and process integrations that are applied or can be implemented in the food industry are of great interest. Reviews on digitalization, internet of things (IoT), additive technologies (3D printing), cloud data storage, smart sensors connected with application of nonthermal and advanced thermal technologies as well as synergy of combination and connective application of nonthermal technologies and advanced thermal technologies will be highly welcomed. Research and review papers on the application of artificial intelligence (AI), deep learning, machine learning, cybersecurity and blockchain future application in nonthermal and advanced thermal processing will be highly welcomed.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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